TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

PCN Number:	**20260706000.1**	**PCN Issued**	July 07, 2026
Qualification of RFAB as an additional Fab site option, Die Revision, Datasheet and MLA as an additional Assembly site options for select devices		**Sample request deadline:**	September 05, 2026
		Estimated 1st ship date:	October 05, 2026
September 05, 2026* will not be supported.			

Change type(s)
Assembly Site
Assembly Process
Assembly Material
Packing/Shipping/Labeling
Design
Data Sheet/Electrical Specification
Wafer Fab Site
Wafer Fab Material
Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site option & MLA as additional Assembly site options for the devices listed below.

Current Fab Site			Additional Fab site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab site**	**Process**	**Wafer Diameter**
MAINEFAB	VIP050	200mm	RFAB	HPA9	300mm

The die was also changed as a result of the process change.

Construction differences are as follows:

	Current Site	**Additional Site**
Assembly/Test site	**TIEM**	**MLA**
Wire bond diam/type	0.9mil Au	0.8mil Cu
Mount compound	8075531	4147858
Mold compound	8096859	4211880
Lead finish	Matte Sn	NiPdAu
Marking appearance (pin 1 ID)	Embossed	Dot

Data sheet update

The datasheets will be changing as a result of the above mentioned changes.
The datasheet change details can be reviewed in the datasheet revision history.
The links to the revised datasheets are available in the table below.

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
June 2026	*	Initial Release. of this data sheet Commercial device split from Automotive data sheet (SNOSAR2).

The LMP860x device is moved from SNOSAR2 "I" revision data sheet to the current standalone datasheet. The changes from the SNOSAR2 "I" revision to this document are as follows:

- Updated the numbering format for tables, figures, and cross-references throughout the document.
- Deleted ESD Classification from the Features section.
- Updated applications with links in Applications section.
- Added Abs Max differential input voltage specification in Absolute Maximum Ratings table.
- Deleted Machine Model ESD rating from ESD Ratings table.
- Updated Thermal Information for D (SOIC) package in Thermal Information table.
- Changed common-mode input impedance for SOIC (D) package in Electrical Characteristics: V_s = 3.3V table.
- Changed differential-mode input impedance for SOIC (D) package in Electrical Characteristics: V_s = 3.3V table.
- Changed typical input bias current specification in Electrical Characteristics: V_s = 3.3V table.
- Changed common-mode input impedance for SOIC (D) package in Electrical Characteristics: V_s = 5V table.
- Changed differential-mode input impedance for SOIC (D) package in Electrical Characteristics: V_s = 5V table.
- Changed typical input bias current specification in Electrical Characteristics: V_s = 5V table.
- Changed Input Bias Current Over Temperature (A2 pin) at VS = 5V curve in Typical Characteristics.
- Added Vos Distribution at Vs =3.3V and Vs =5V plots for SOIC (D) package in Typical Characteristics.
- Added Vos drift vs Temperature plots for SOIC (D) package in Typical Characteristics.
- Added Gain Error Distribution plots for SOIC (D) package in Typical Characteristics.
- Added Gain drift vs Temperature plots for SOIC (D) package in Typical Characteristics.
- Added CMMR Distribution plots for SOIC (D) package in Typical Characteristics.
- Added CMRR drift vs Temperature plots for SOIC (D) package in Typical Characteristics.
- Added the Related Documentation section.

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
LMP8601, LMP8602, LMP8603	SNOSAR2I	SLVSJ15	LMP860x , –22V to 60V, Bidirectional Current Sense Amplifier With In-Line Filter Capability datasheet

Qual details are provided in the Qual Data Section.
Test coverage, insertions, conditions will remain consistent with current testing.

Reason for Change:	Supply Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability:	These devices include new die based on existing schematics in a larger diameter wafer fab with a die shrink. There are changes in the electrical tables. Physical aspects of the device have changed. Review updated datasheets and/or the Standard Data Packet for more details on the changes. Evaluating samples is encouraged.
Impact on Environmental	Checked boxes indicate the status of

Ratings

environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
MAINEFAB	CUA	USA	South Portland
RFAB	**RFB**	**USA**	**Richardson**

Die Rev:

Current	**New**
Die Rev [2P]	**Die Rev [2P]**
A	**A**

Assembly Site Information

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TIEM	CU6	MYS	Melaka
MLA	**MLA**	**MYS**	**Kuala Lumpur**

Sample product shipping label (not actual product label):

Products Affected:

LMP8601MAX/NOPB	LMP8602MAX/NOPB	LMP8603MAX/NOPB

Qualification Report
Automotive Qualification Summary
(As per AEC-Q100 Rev. J and JEDEC Guidelines)
Approve Date 31-March-2026

Product Attributes

Attributes	Qual Device: LMP8603QMAX/NOPB	Qual Device: LMP8602QMAX/NOPB	Qual Device: LMP8601QMAX/NOPB	QBS Process Reference: INA229AQDGSRQ1	QBS Package Reference: TLV9064QDRQ1	QBS Package Reference: OPA4991QDRQ1	QBS Package Reference: TLC555QDRQ1	QBS Product Reference: TLC555QDRQ1	QBS Package Reference: OPA2991QDRQ1	QBS Product Reference: TLC3555QDRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Signal Chain	Signal Chain	Signal Chain	Signal Chain	Signal Chain	Signal Chain	Signal Chain	Signal Chain	Signal Chain	Signal Chain
Wafer Fab Supplier	RFAB	RFAB	RFAB	RFAB	RFAB	RFAB	RFAB	RFAB	RFAB	RFAB
Assembly Site	MLA	MLA	MLA	ASESHAT	MLA	MLA	FMX	MLA	FMX	FMX
Package Group	SOIC	SOIC	SOIC	VSSOP	SOIC	SOIC	SOIC	SOIC	SOIC	SOIC
Package Designator	D	D	D	DGS	D	D	D	D	D	D
Pin Count	8	8	8	10	14	14	8	8	8	8

QBS: Qual By Similarity, also known as Generic Data
Qual Device LMP8603QMAX/NOPB is qualified at MSL1 260C
Qual Device LMP8602QMAX/NOPB is qualified at MSL1 260C
Qual Device LMP8601QMAX/NOPB is qualified at MSL1 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: LMP8603QMAX/NOPB	Qual Device: LMP8602QMAX/NOPB	Qual Device: LMP8601QMAX/NOPB	QBS Process Reference: INA229AQDGSRQ1	QBS Package Reference: TLV9064QDRQ1	QBS Package Reference: OPA4991QDRQ1	QBS Package Reference: TLC555QDRQ1	QBS Product Reference: TLC555QDRQ1	QBS Package Reference: OPA2991QDRQ1	QBS Product Reference: TLC3555QDRQ1
Test Group A - Accelerated Environment Stress Tests																	
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	1/80/0	-	-	-	-	1/80/0	1/132/0	1/80/0	3/924/0	1/80/0
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	-	-	-	3/231/0	3/231/0	-	-	-	-	-
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	1/77/0	-	-	3/231/0	3/231/0	3/231/0	1/77/0	1/77/0	3/231/0	1/77/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	-	-	-	-	3/231/0	-	-	-	-
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	-	-	3/231/0	3/231/0	-	1/77/0	1/77/0	3/231/0	1/77/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	-	-	3/231/0	3/231/0	1/77/0	1/109/0	1/77/0	3/231/0	1/77/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	1/5/0	-	-	1/5/0	-	-	-	-	1/5/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/135/0	-	1/50/0	1/45/0	3/135/0	1/45/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	1/77/0	-	-	3/231/0	-	1/45/0	-	-	-	-
Test Group B - Accelerated Lifetime Simulation Tests																	
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	-	-	3/231/0	3/231/0	-	-	-	-	-
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	300 Hours	3/231/0	-	-	-	-	-	-	-	-	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0	3/2400/0	-	-	-	-	-
EDR	B3	AEC Q100-005	1	77	NVM Endurance, Data Retention, and Op Life	Per QSS-009-018	1 Step	3/231/0	-	-	-	-	-	-	-	-	-
Test Group C - Package Assembly Integrity Tests																	
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	-	-	-	3/90/0	1/30/0	1/30/0	-	3/90/0	-
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	-	-	-	3/90/0	1/30/0	1/30/0	-	3/90/0	-
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-	-	-	1/15/0	-	1/15/0	-	-	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	1/15/0	-	-	-	1/15/0	-	1/15/0	-	-	-
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	1/10/0	-	-	-	3/30/0	-	1/10/0	-	3/30/0	-
Test Group D - Die Fabrication Reliability Tests																	
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests																	
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	1/3/0	-	-	-	-	-	-	-	-	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	1000 Volts	1/3/0	-	-	-	-	-	-	-	-	-
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	1/3/0	-	-	-	-	-	-	-	-	-
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	1/30/0	1/30/0	1/30/0	-	-	-	-	-	-	-

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Ambient Operating Temperature by Automotive Grade Level:
Grade 0 (or E): -40C to +150C
Grade 1 (or Q): -40C to +125C
Grade 2 (or T): -40C to +105C
Grade 3 (or I) : -40C to +85C
E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room : AC/uHAST
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-NPD-2405-032

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.